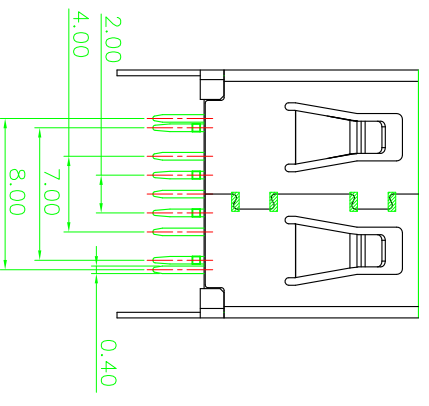
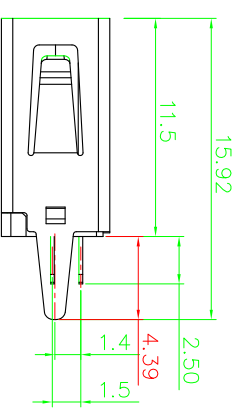
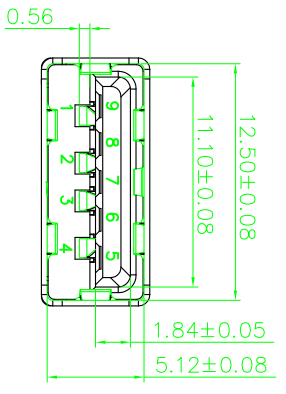
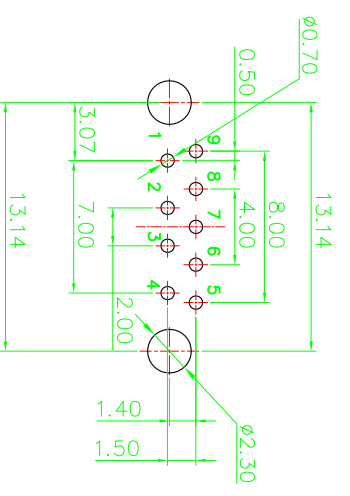
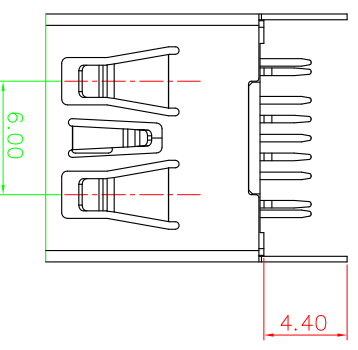


MAPX	MODIFICATION	DATE
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- NOTES:
- 1.MATERIAL:
 1.1 HOUSING: HIGH TEMPERATURE THERAL PLASTIC.
 1.2 SPRING CONTACT: COPPER ALLOY.
 1.3 FLAT CONTACT: COPPER ALLOY
 1.4 SHELL : COPPER ALLOY
 1.5 COVER: HIGH TEMPERATURE THERAL PLASTIC.
- 2.FINISH:
 2.1 CONTACT: (SEE P/N.), [50 μ m] MIN. NICKEL UNDERPLATING OVER ALL.
 2.2 SHELL: [50 μ m] MIN. SOLDERABILITY NICKEL UNDERPLATING OVER ALL.



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	SIDA_SSRX-
6	SIDA_SSRX+
7	GND_DRAIN
8	SIDA_SSTX-
9	SIDA_SSTX+
Shell	Shield

ITEM	PART NAME	Material	Q'TY	REMARK
1	Shell	C2680	1	T=0.3
2	4Pin Contact	C5191	4	T=0.25 Plating Gold/Tin
3	5Pin Contact	C2680	5	T=0.25 Plating Gold/Tin
4	Housing	LCP+30%GF	1	Blue UL94V-0
5	COVER	LCP+30%GF	1	Blue UL94V-0

深圳市精拓金电子有限公司

产品图 PRODUCT CHART DWG 公差一览表 TOLERANCE UNLESS OTHERWISE		单位 UNITS MM	制图 DRAWING Gavin	制图料号 PRODUCT PART NO. USB 3.0, A TYPE, H=11.5mm, 直插无边CONNECTOR.
X	±0.35	X	±5°	
X	±0.30	X	±2°	
XX	±0.20	XX	±1°	
XXX	±0.10	XXX	±0.5°	
日期 DATE 2015-04-23		审核 CHECK 郭治富	核准 APPR 黄国荣	角法 VIEW 第三角
			版本 VER A0	